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ON Semiconductor®

FDD9410-F085

N-Channel Power Trench® MOSFET 40 V, 50 A, 4.1 m Ω

Features

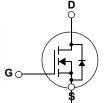
- Typ $r_{DS(on)}$ = 3.5 m Ω at V_{GS} = 10V, I_D = 50 A
- \blacksquare Typ Q_{g(tot)} = 23.5 nC at V_{GS} = 10V, I_D = 50 A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Integrated Starter/alternator
- Primary Switch for 12V Systems



G



D

(TO-252)

MOSFET Maximum Ratings $T_J = 25$ °C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain to Source Voltage		40	V
V _{GS}	Gate to Source Voltage		±20	V
I _D	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	50	^
	Pulsed Drain Current	T _C = 25°C	See Figure4	Α
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	40	mJ
D	Power Dissipation		75	W
P_{D}	Derate Above 25°C		0.5	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance Junction to Case		2	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient	(Note 3)	52	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD9410	FDD9410-F085	D-PAK(TO-252)	13"	12mm	2500 units

- 1: Current is limited by bondwire configuration.
- 2: Starting T_J = 25°C, L = 50uH, I_{AS} = 40A, V_{DD} = 40V during inductor charging and V_{DD} = 0V during time in avalanche.

 3: R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Units

Max

Тур

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Parameter

Off Cha	aracteristics					
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40	-	-	V
1	Drain to Source Leakage Current	$V_{DS} = 40V$, $T_J = 25^{\circ}C$	-	-	1	μΑ

Test Conditions

Min

B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0$	/ 40	-	-	V
I _{DSS}	Drain to Source Leakage Current	$V_{DS} = 40V$, $T_J = 2$.5°C -	-	1	μΑ
		$V_{GS} = 0V$ $T_J = 1$	75°C(Note 4) -	-	1	mA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.0	4.0	V
-	Drain to Source On Resistance	I _D = 50A,	$T_{J} = 25^{\circ}C$	-	3.5	4.1	$m\Omega$
DS(on)		$V_{GS} = 10V$	$T_J = 175^{\circ}C(Note 4)$	-	6.1	7.1	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	-V _{DS} = 25V, V _{GS} = 0V, -f = 1MHz		-	1715	-	pF
C _{oss}	Output Capacitance			-	453	-	pF
C _{rss}	Reverse Transfer Capacitance			-	28	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.3	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V_{GS} = 0 to 10V	V _{DD} = 20V	-	23.5	34.5	nC
$Q_{g(th)}$	Threshold Gate Charge	V_{GS} = 0 to 2V	I _D = 50A	-	3.2	4	nC
Q_{gs}	Gate to Source Gate Charge		_	-	9.6	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	4.4	-	nC

Switching Characteristics

t _{on}	Turn-On Time	V_{DD} = 20V, I_{D} = 50A, V_{GS} = 10V, R_{GEN} = 6Ω	-	-	38	ns
t _{d(on)}	Turn-On Delay Time		-	12	-	ns
t_r	Rise Time		-	12	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	20	-	ns
t _f	Fall Time		-	9	-	ns
t _{off}	Turn-Off Time		-	-	45	ns

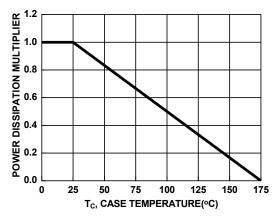
Drain-Source Diode Characteristics

V _{SD} Source to Drain Diode Voltage	Source to Drain Diede Voltage	I _{SD} = 50A, V _{GS} = 0V	-	-	1.25	V
	Source to Drain Diode Voltage	$I_{SD} = 25A, V_{GS} = 0V$	-	-	1.2	V
T _{rr}	Reverse Recovery Time	$I_F = 50A$, $dI_{SD}/dt = 100A/\mu s$,	-	44	58	ns
Q _{rr}	Reverse Recovery Charge	V _{DD} =32V	-	31.5	41	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



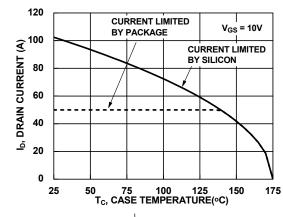


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs.

Case Temperature

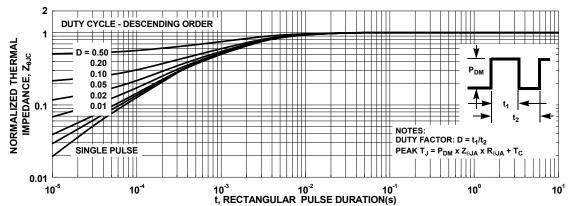


Figure 3. Normalized Maximum Transient Thermal Impedance

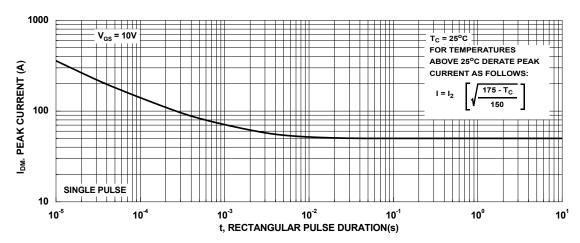


Figure 4. Peak Current Capability

Typical Characteristics

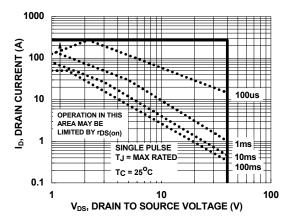
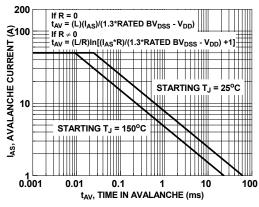


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to On Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

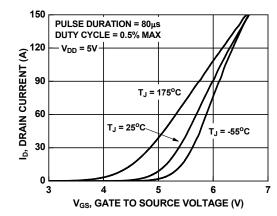


Figure 7. Transfer Characteristics

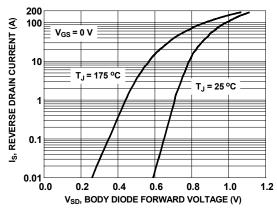


Figure 8. Forward Diode Characteristics

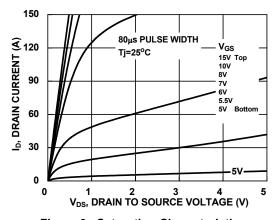


Figure 9. Saturation Characteristics

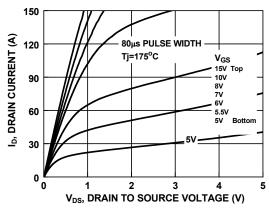


Figure 10. Saturation Characteristics

Typical Characteristics

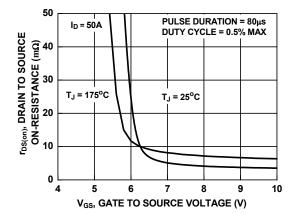


Figure 11. R_{DSON} vs. Gate Voltage

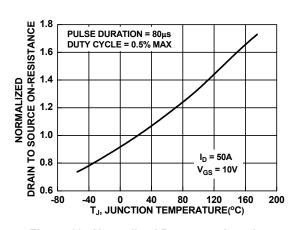


Figure 12. Normalized R_{DSON} vs. Junction Temperature

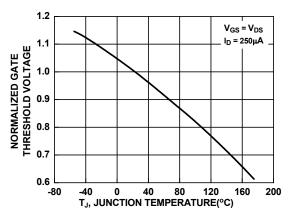


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

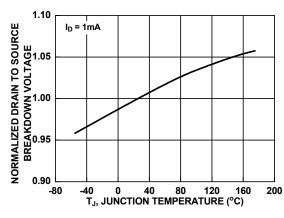


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

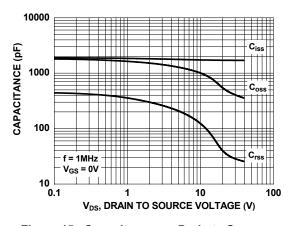


Figure 15. Capacitance vs. Drain to Source Voltage

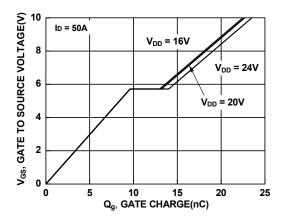


Figure 16. Gate Charge vs. Gate to Source Voltage

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